

RELIABILITY REPORT
FOR
MAX11203EEE+
PLASTIC ENCAPSULATED DEVICES

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MAXIM INTEGRATED

160 RIO ROBLES
SAN JOSE, CA 95134

Approved by
Sokhom Chum
Quality Assurance
Reliability Engineer

Conclusion

The MAX11203EEE+ successfully meets the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

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I. Device Description

A. General

The MAX11203/MAX11213 are ultra-low-power (< 300 μ A active current), high-resolution, serial-output ADCs. These devices provide the highest resolution per unit power in the industry, and are optimized for applications that require very high dynamic range with low power, such as sensors on a 4mA to 20mA industrial control loop. Optional input buffers provide isolation of the signal inputs from the switched capacitor sampling network allowing these converters to be used with high-impedance sources without compromising available dynamic range or linearity. The devices provide a high-accuracy internal oscillator that requires no external components. When used with the specified data rates, the internal digital filter provides more than 100dB rejection of 50Hz or 60Hz line noise. The devices are configurable using the SPI interface and include four GPIOs that can be used for external mux control. The MAX11213 includes digital programmable gain of 1 to 128.

The MAX11203/MAX11213 operate over the -40°C to +85°C temperature range, and are available in a 16-pin QSOP package.

II. Manufacturing Information

A. Description/Function:	16-Bit, Single-Channel, Ultra-Low Power, Delta-Sigma ADC with Programmable Gain and GPIO
B. Process:	TS18
C. Number of Device Transistors:	148241
D. Fabrication Location:	Taiwan
E. Assembly Location:	Philippines, Thailand
F. Date of Initial Production:	June 25, 2010

III. Packaging Information

A. Package Type:	16-pin QSOP
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-4018
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	120°C/W
K. Single Layer Theta Jc:	37°C/W
L. Multi Layer Theta Ja:	103.7°C/W
M. Multi Layer Theta Jc:	37°C/W

IV. Die Information

A. Dimensions:	48.5X76.5 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	0.18um
F. Minimum Metal Spacing:	0.18um
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Don Lipps (Manager, Reliability Engineering) Bryan Preeshl (Vice President of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% for all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 93 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 11.8 \times 10^{-9}$$

$$\lambda = 11.8 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maximintegrated.com/qa/reliability/monitor>. Cumulative monitor data for the TS18 Process results in a FIT Rate of 0.11 @ 25C and 1.87 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (lot QYYZCQ002B, DC 1013)

The AC84 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250mA and overvoltage per JEDEC JESD78.

Table 1
Reliability Evaluation Test Results

MAX11203EEE+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135°C	DC Parameters	45	0	QYYZCQ002J, D/C 1013
	Biased	& functionality	48	0	NNWBCA010A, D/C 0504
	Time = 192 hrs.				

Note 1: Life Test Data may represent plastic DIP qualification lots.